

256K X 32 SRAM Module**Features**

- 4.5V - 5.5V Operation
- Variable speed CMOS SRAMs modules
- Low active power
—2.64W (max.)
- Low standby power
—11.0 mW (max.)
- Automatic power-down when deselected
- High Density 8 mega bit SRAM module
- SMD Technology
- TTL-compatible inputs and outputs
- Easy memory expansion with CE and $\overline{OE}$ options
- Data Retention Function
- Fully Static No Clocks

High Density Packaging

- Available in 64 -pin ZIP version
- Single +5V($\pm 10\%$) Supply Operation

Functional Description

The IMM1841 are high performance 8-megabit static RAM modules. Four chip select ($\overline{CS1}$, $\overline{CS2}$, $\overline{CS3}$, $\overline{CS4}$) are used to independently enable the four bytes. Reading or writing can be executed on individual bytes or any combination of multiple bytes through proper use of chip selects

Writing to each byte is accomplished by taking appropriate Chip enable ($\overline{CE}$) and Write enable ($\overline{WE}$) inputs LOW. Data on the eight I/O pins(I/O_0 through I/O_{31}) is then written into the location specified on the address pins (A_0 through A_{17}).

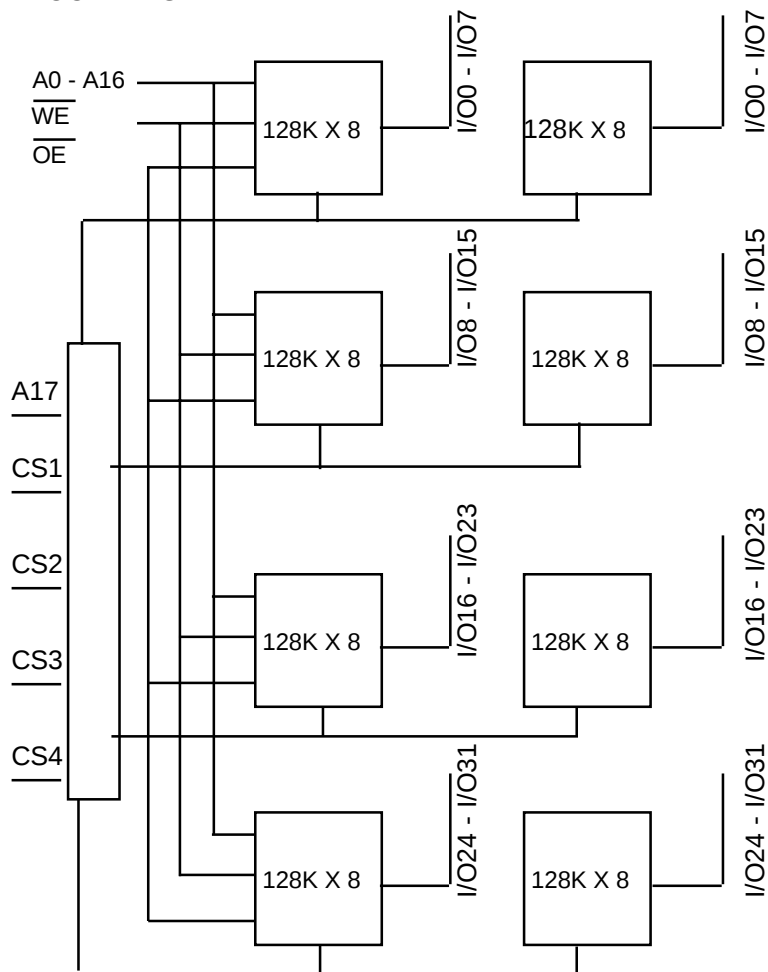
Reading from the device is accomplished by taking Chip enable ($\overline{CE}$) and Output enable ($\overline{OE}$) LOW while forcing Write enable ($\overline{WE}$) HIGH for read. Under these conditions, the contents of the memory location specified by the address pins will appear on the I/O pins.

The thirty two input/output pins(I/O_0 through I/O_{31}) are placed in a high-impedance state when the device is deselected ($\overline{CE}$ HIGH), the outputs are disabled ($\overline{OE}$ HIGH), or during a write operation ($\overline{CE}$ LOW, and $\overline{WE}$ LOW).

Two pins PD0 and PD1 are used to identify module memory density in applications where alternate versions of the JEDEC standard modules can be interchanged. The IMM1841 utilizes corner power and ground SRAM's

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BLOCK DIAGRAM



PIN CONFIGURATION

	1	GND
PD0	2	
	3	PD1
I/O0	4	
I/O1	5	I/O8
I/O2	6	7 I/O9
I/O3	8	9 I/O10
VCC	10	11 I/O11
A7	12	13 A0
A8	14	15 A1
A9	16	17 A2
I/O4	18	19 I/O12
I/O5	20	21 I/O13
I/O6	22	23 I/O14
I/O7	24	25 I/O15
WE	26	27 GND
A14	28	29 A15
CS1	30	31 CS2
	32	
CS3	33	CS4
A16	34	
GND	35	A17
I/O16	36	OE
I/O17	37	
I/O18	38	
I/O19	39	I/O24
A10	40	41 I/O25
A11	42	43 I/O26
A12	44	45 I/O27
A13	46	
I/O20	47	A3
I/O21	48	49 A4
I/O22	50	51 A5
I/O23	52	53 VCC
	54	55 A6
	56	57 I/O28
	58	59 I/O29
	60	61 I/O30
	62	63 I/O31
GND	64	

Pin Names

A0 – A17	Address Inputs
CS1- CS4	Chip Enable
WE	Write Enable
OE	Output Enable
I/O0 – I/O31	Data Input/Output
Gnd	Ground
Vcc	Power Supply +5V
PD0-PD1	Memory Density Identifier

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Selection Guide

	IMM1841-35	IMM1841-45
Maximum Access time	35	45
Maximum Operating Current	960	960
Maximum CMOS Standby Current (mA)	480	480

Maximum Ratings (Above which the useful life may be impaired. For user guide lines, not tested)

Storage Temperature.....-55°C to +125°C
Ambient Temperature..... 0°C to 85°C
Supply voltage on Vcc relative to Gnd.....-0.5 V to 7.0V
Current into Outputs (LOW).....20mA
DC Input Voltage.....0.5 v to Vcc + 0.5V

Operating Range

Range	Ambient Temperature	Vcc
Commercial	0°C to 70°C	4.5V - 5.5V

Electrical Characteristics

Parameter	Description	Test Condition	Min.	Max.	Unit
V_{OH}	Output HIGH voltage	$V_{CC} = \text{Min}, I_{OH} = -4\text{mA}$	2.4		V
V_{OL}	Output LOW voltage	$V_{CC} = \text{Min}, I_{OL} = 8\text{mA}$		0.4	V
V_{IH}	Input HIGH Voltage		2.2	V_{CC}	
V_{IL}	Input LOW Voltage		-0.5	0.8	V
I_{IX}	Input Load Current	$\text{Gnd} < V_I < V_{CC}$	-16	16	mA
I_{OZ}	Output Leakage Current	$\text{Gnd} < V_O < V_{CC}$, Output Disable	-10	10	mA
I_{CC}	Vcc Operating	$V_{CC} = \text{Max.}, I_{OUT} = 0\text{mA}$		960	mA
	Supply Current	$\overline{CS} < V_{IL}$			
I_{SB1}	Automatic $\overline{CE}$	$\text{Max } V_{CC}, \overline{CE} > V_{IH}$		480	mA
	Power-Down Current	$V_{IN} > V_{IH}$ or $V_{IN} < V_{IH}$, Min Duty			
	TTL Inputs	cycle = 100%			
I_{SB2}	Automatic $\overline{CE}$	$\text{Max } V_{CC}, \overline{CE} > V_{CC} - 0.2$		200	mA
	Power-Down Current	$V_{IN} > V_{CC} - 0.2$, or $V_{IN} < 0.2$			

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Switching Characteristics

over the Operating Range

Parameter	Description	IMM1841- 35		IMM1841- 45		Unit
		Min.	Max.	Min.	Max.	
t _{RC}	Read Cycle Time	35		45		ns
t _{AA}	Address to Data Valid		35		45	ns
t _{OHA}	Data Hold from Address Change	3		3		ns
t _{ACE}	$\overline{\text{CE}}$ LOW to Data Valid		35		35	ns
t _{DOE}	$\overline{\text{OE}}$ LOW to Data Valid		25		30	ns
t _{LZOE}	$\overline{\text{OE}}$ LOW to Low Z ^[8]	0		0		ns
t _{HZOE}	$\overline{\text{OE}}$ HIGH to High Z ^[7,8]		15		15	ns
t _{LZCE}	$\overline{\text{CE}}$ LOW to Low Z ^[8]	10		10		ns
t _{HZCE}	$\overline{\text{CE}}$ HIGH to High Z ^[7,8]		20		20	ns
t _{PD}	$\overline{\text{CE}}$ HIGH to Power-Down		35		45	ns
t _{WC}	Write Cycle Time	35		45		ns
t _{SCE}	$\overline{\text{CE}}$ LOW to Write End	35		40		ns
t _{AW}	Address Set-Up to Write End	30		40		ns
t _{HA}	Address Hold from Write End	2		2		ns
t _{SA}	Address Set-up to write start	2		2		ns
t _{PWE}	WE Pulse Width	30		35		ns
t _{SD}	Data Set-up to Write End	20		25		ns
t _{HD}	Data Hold from Write End	2		2		ns
t _{LZWE}	$\overline{\text{WE}}$ HIGH to LOW Z ^[8]	0		0		ns
t _{HZWE}	$\overline{\text{WE}}$ LOW to High Z ^[7,8]	0	15	0	15	ns

Notes:

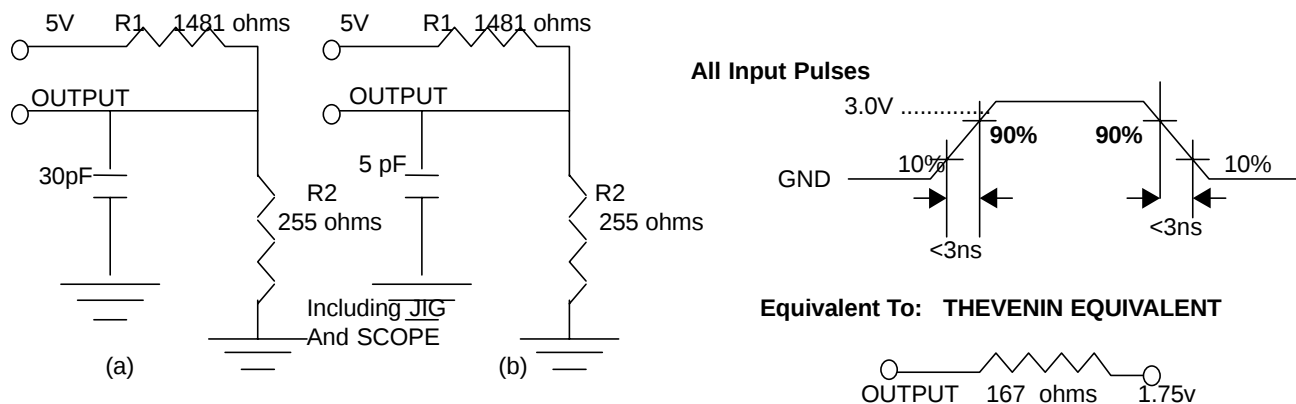
1. A pullup resistor on CS input is required to keep the device deselected during V_{CC} power-up, otherwise I_{SB} will exceed values
2. 20 pF on CS and 70 pF on all others

Capacitance

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	T _A = 25°C, f = 1 MHz, V _{CC} = 5.0V	70/20	pF
C _{OUT}	Output Capacitance		20	pF

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AC Test Loads and Waveforms

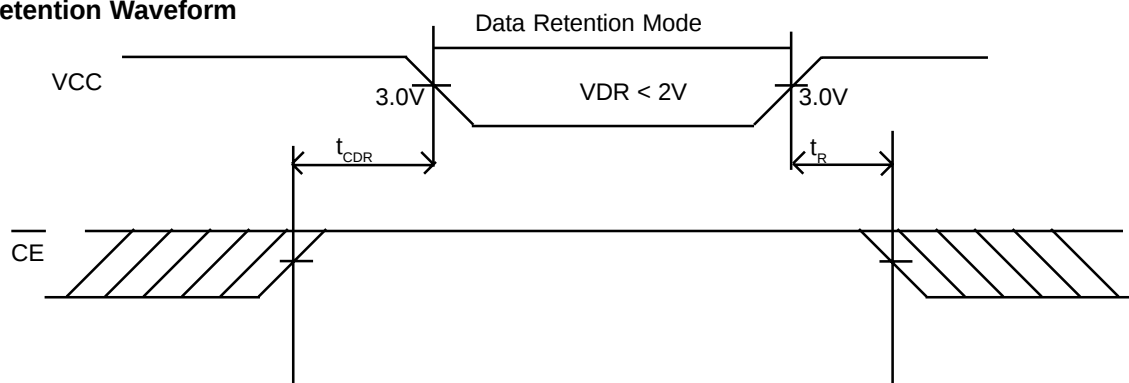


Data Retention Characteristics

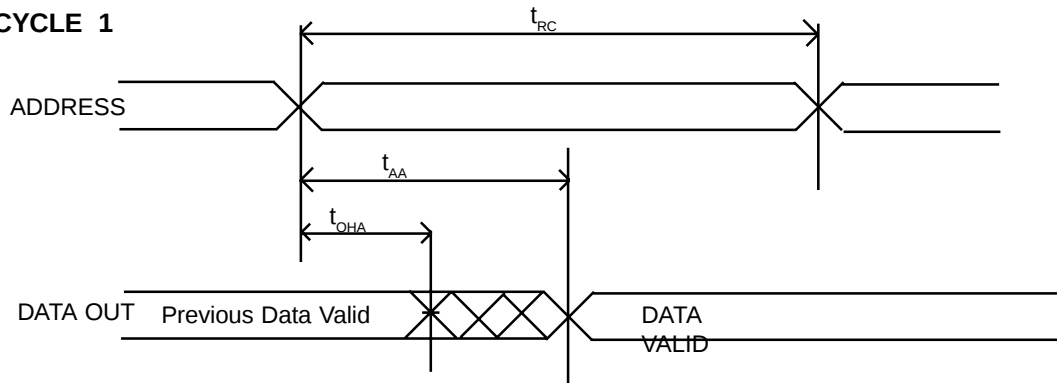
over the Operating Range

Parameter	Description		Test Conditions	Min.	Typ ^[3]	Max.	Unit
V_{DR}	V_{CC} for Data Retention			2.0			V
I_{CCDR}	Data Retention Current	Com'I	No input may exceed $V_{CC} + 0.3V$			1.7	mA
			$V_{CC} = V_{DR} = 3.0V$, $\overline{CE} \geq V_{CC} - 0.3V$		16	200	μA
		L	$V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$				
$t_{CDR}^{[5]}$	Chip Deselect to Data Retention Time			0			ns
t_R	Operation Recovery Time			t_{RC}			ns

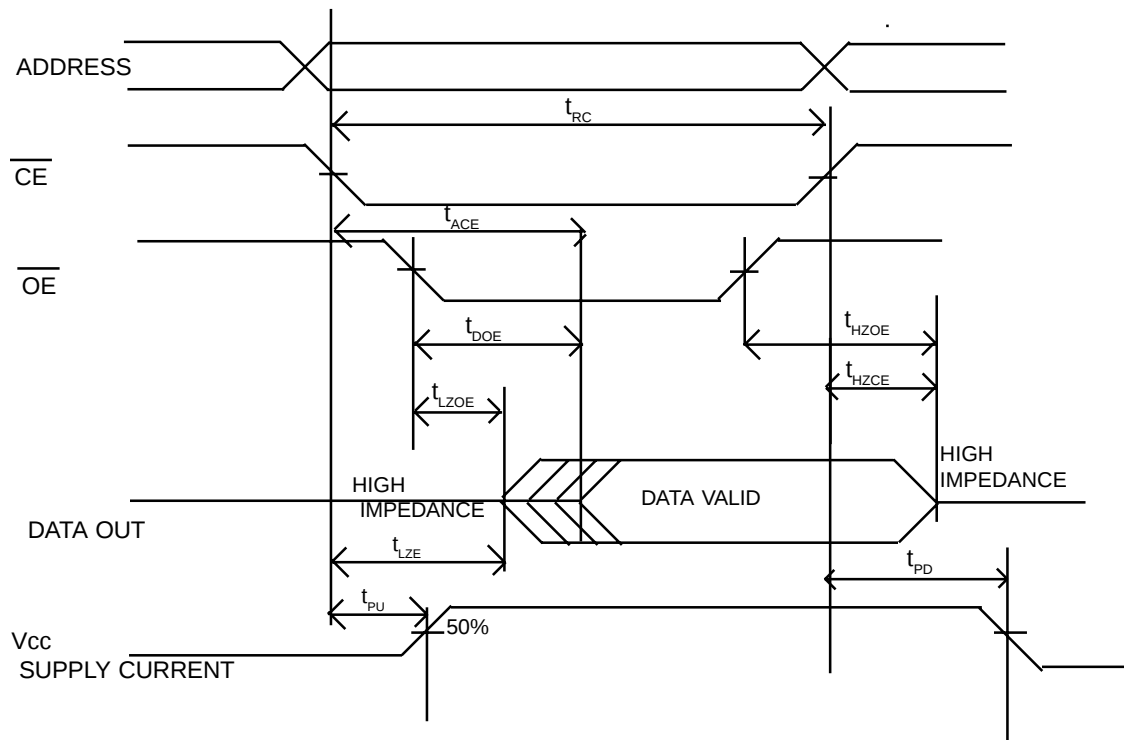
Data Retention Waveform



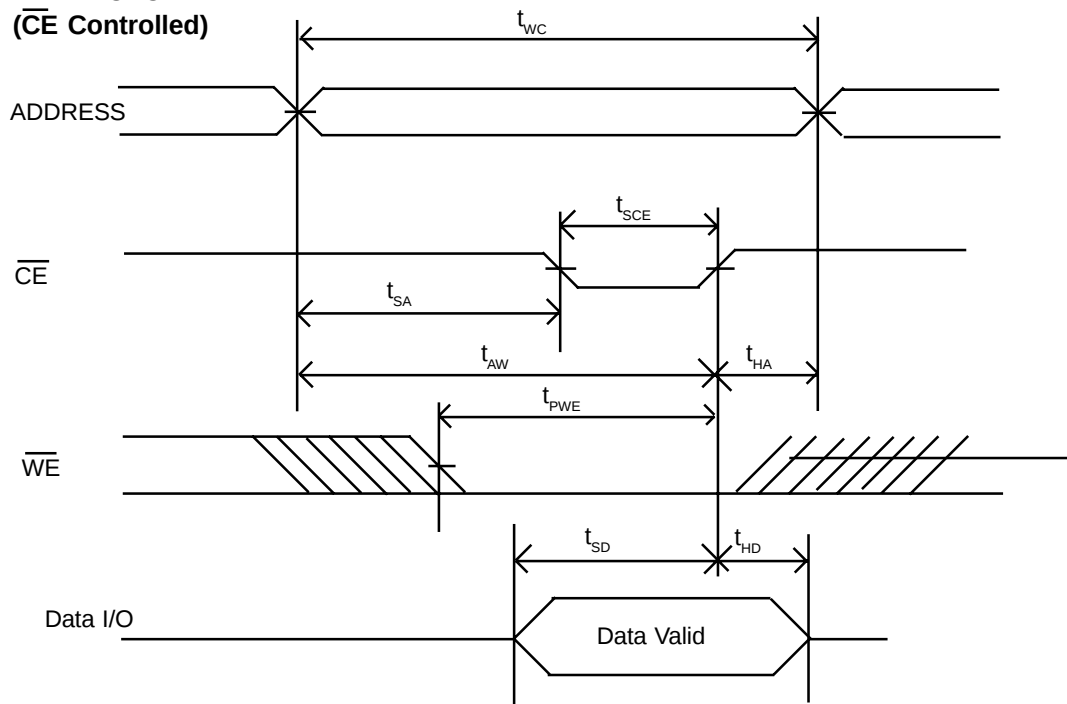
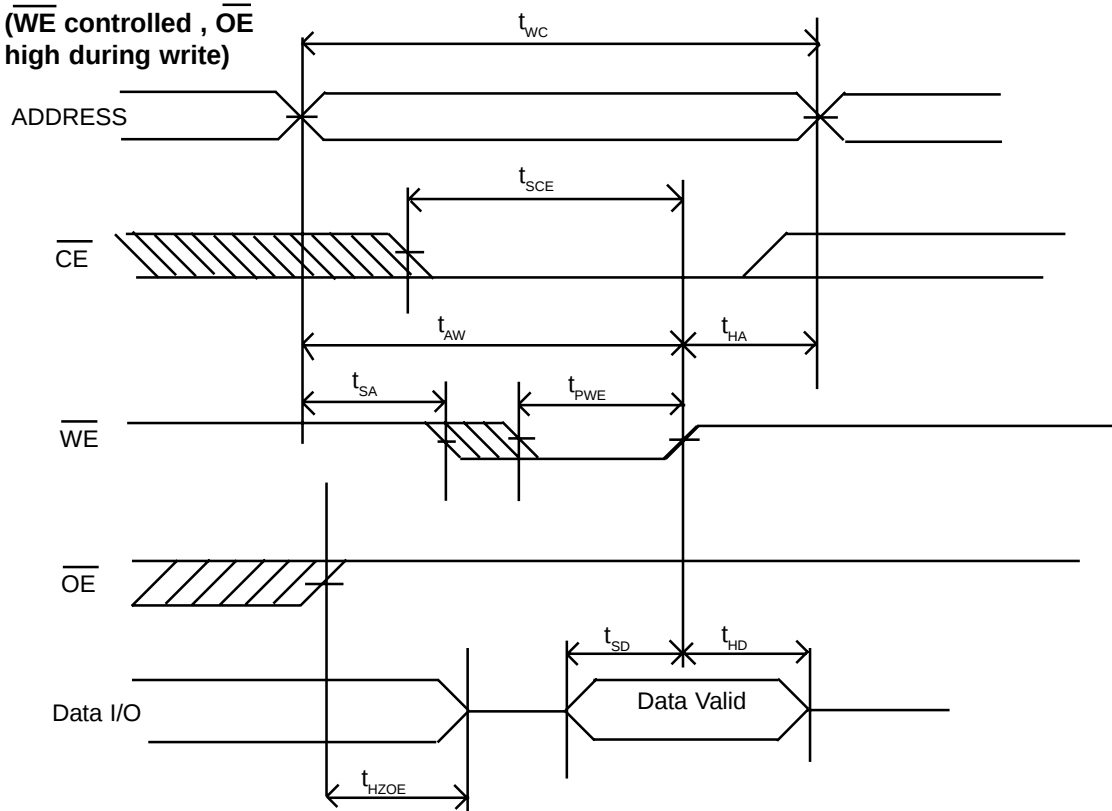
READ CYCLE 1

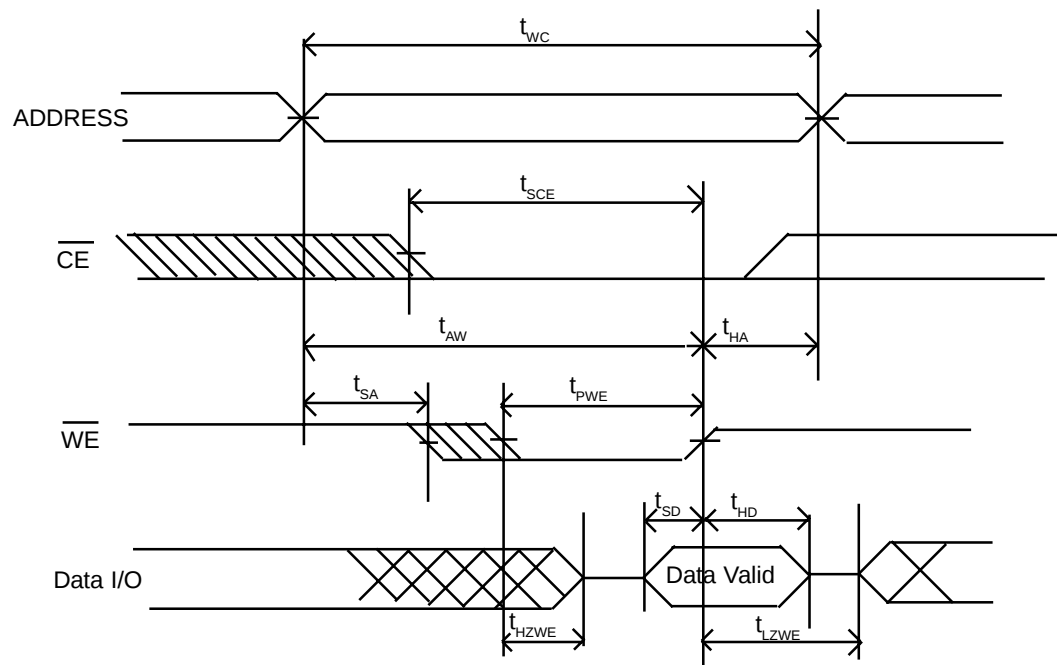


READ CYCLE 2



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**WRITE CYCLE 1
($\overline{\text{CE}}$ Controlled)**

**WRITE CYCLE 2
($\overline{\text{WE}}$ controlled, $\overline{\text{OE}}$ high during write)**


**WRITE CYCLE 3
(WE controlled, OE LOW)**

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Truth Table

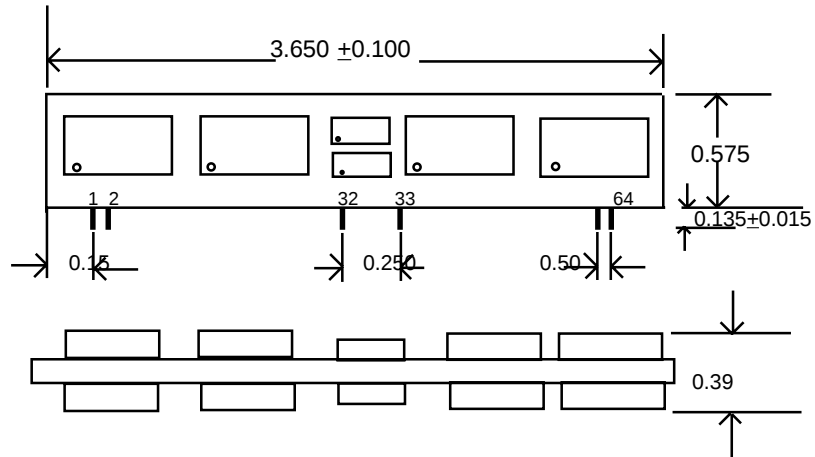
$\overline{\text{CE}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	I/O0-I/O31	Mode	Power
H	X	X	High Z	Power-Down	Standby (I_{SB})
L	L	H	Data Out	Read	Active (I_{CC})
L	X	L	Data In	Write	Active (I_{CC})
L	H	H	High Z	Selected, Outputs Disabled	Active (I_{CC})

Ordering Information

Speed(ns)	Ordering Code	Package Type
45	IMM1841APZ-45C	64- PIN Plastic ZIP Module
35	IMM1841APZ-35C	64- PIN Plastic ZIP Module

C

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All dimensions in inches